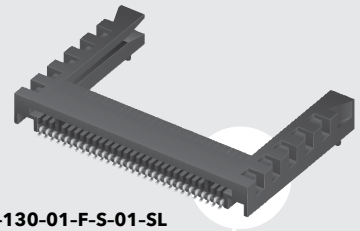
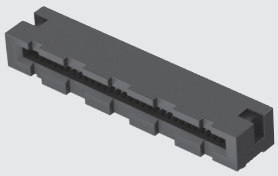
samtec



MB1-130-01-F-S-01-SL



MB1-130-01-F-S-01-SL-N

(1.00 mm) .0394"

MB1 SERIES

MINI EDGE CARD SOCKET WITH GUIDES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MB1

Insulator Material:
Black LCP
Contact Material:
BeCu
Plating:
Sn or Au over
50 µ" (1.27 µm) Ni
Current Rating:
2.4 A per pin
(2 pins powered)
Voltage Rating:
250 VDC/354 VDC
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(5.26 mm) .207" to
(6.10 mm) .240"
RoHS Compliant:
Yes

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (20-30)
(0.15 mm) .006" max (40-50)*
*(.004" stencil solution may be available; contact ipg@samtec.com)

RECOGNITIONS

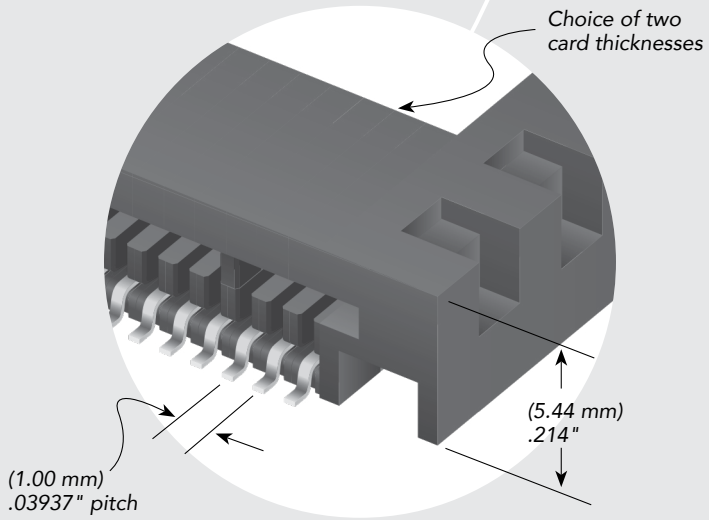
For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

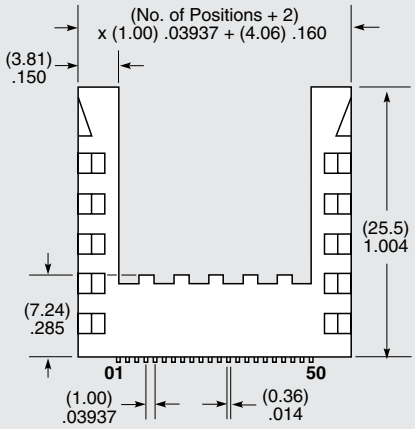
ALSO AVAILABLE (MOQ Required)

- Other platings

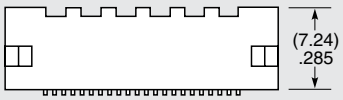
Mates with:
(0.80 mm) .031" PCB,
(1.60 mm) .062" PCB



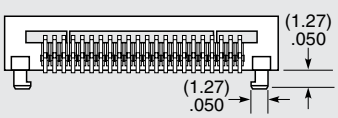
MB1	–	1	NO. OF PINS	–	01	–	PLATING OPTION	–	S	–	CARD SLOT	–	SL	–	OTHER OPTION
			20, 30, 40, 50				–F = Gold flash on contact, Matte Tin on tail –L = 10 µ" (0.25 µm) Gold on contact, Matte Tin on tail				Specify CARD SLOT from chart				–N = No Card Guides

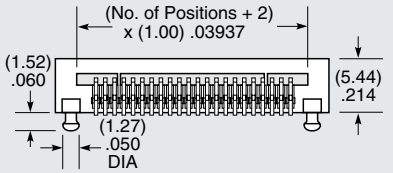


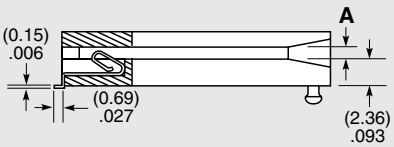
CARD SLOT	A	MATES WITH BOARD THICKNESS
-01	(0.97) .038	(0.80) .031
-02	(1.83) .072	(1.60) .062



-N OPTION







Important Note: Samtec recommends that pads on the mating board be Gold plated.

Note:
Some sizes, styles and options are non-standard, non-returnable.

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.